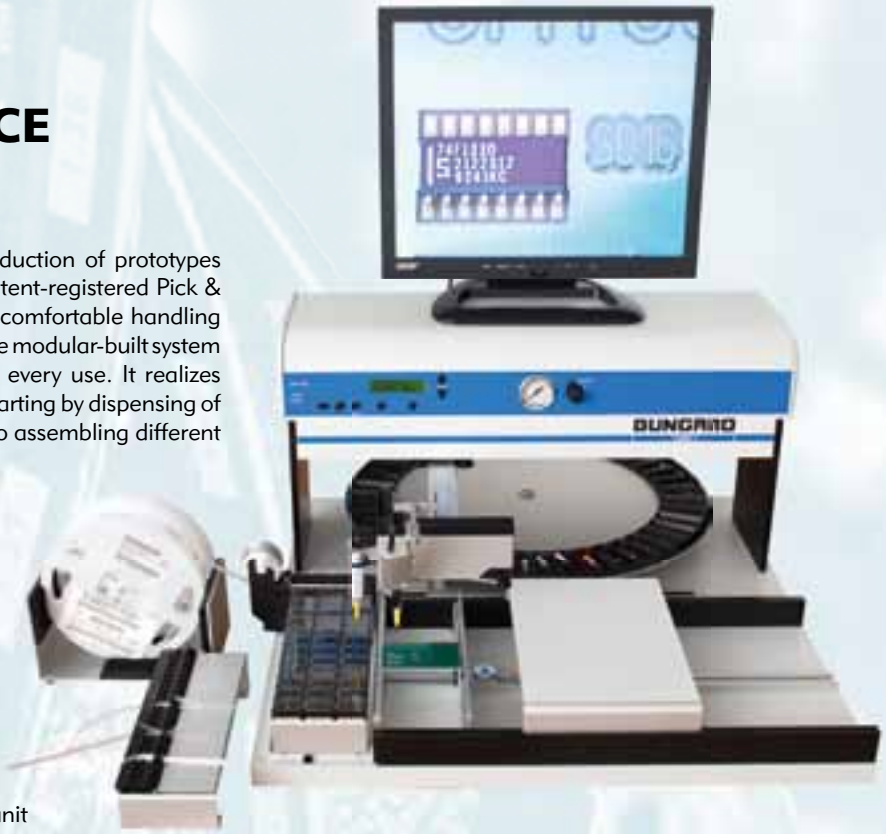
BUNGARD PICK&PLACE SMT3000

Manipulator for the production of prototypes and small series. The patent-registered Pick & Place head enables the comfortable handling of SMD-components. The modular-built system can be configurated for every use. It realizes the complete process - starting by dispensing of solder paste or glue up to assembling different components.



Features:

- Ergonomic
- Integrated dispenser unit
- Camera fixture
- X/Y-locking device
- Head lightening
- PCB holders
- Desktop workplace
- High end quality

Vision system

By means of a camera attached directly to the assembly head, you can view the entire pick & place process – enlarged on a monitor.

X/Y-locking device

The X/Y locking device ensures precision mounting. Individual movement axes can be locked. An automatic function independently locks the X and Y axes when the components are lowered or when placing a dispenser dot. This makes it particularly easy to place Melfs.

Head lightening

The dual LED-light of the pick and place area can be integrated optional. The LEDs are placed on both sides of the nozzle and enable the constant and permanent lightening under the assembling head.

The integration into the control mode of the Manipulator allows the menu routed activating - depending on application.

PCB holders

All manipulators have a universal circuit board holder by standard for single- or double-sided PCBs. Elastic holding fingers are adjustable and hold the board in place. Large PCBs can be handled on demand. Customer-specific holders can be adapted or realised directly at our plant.

SMT 3000

Assembling:	300-600 SMDs/hour
Dimensions (LxWxH):	600 x 600 x 345 mm
Max. outreach (LxWxH):	600 x 1100 x 345 mm
Max. PCB size (LxW):	440 x 245 mm
Max. assembling area (LxW):	350 x 245 mm
PCB thickness:	0,5 mm bis ~ 4 mm
Height underneath PCB:	min. 39 mm, max. 50 mm
Components:	Chip 0201 bis QFP 0,65 mm pitch
Max. component height:	approx. 16 mm
Hub of assembling head:	max. 26 mm
Rotation angle:	0-360°
Weight:	approx. 23 kg
Power supply:	100- 230 V AC, aautomatical
Input:	max. 50 VA

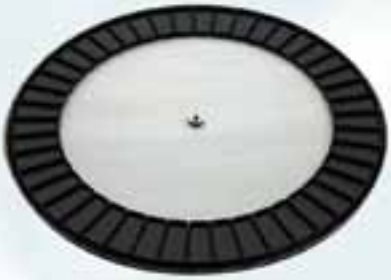
(Only by dispensing unit):
clean, oil-free compressed-air, max. 4 bar,
1,5 l/min consumption while dispensing
pressure connector for tube iØ 4mm, oØ 6mm

COMPONENT FEEDER

The system enables the feeding of components in tapes as well as loose components.

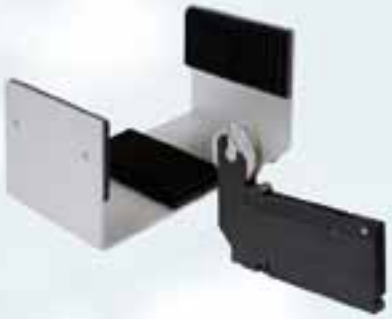
Carousel

The antistatic manual carousel with 45 shelves feeds loose components in a comfortable way.



Tapefeeder

Tape feeders supply you with large amounts of standard components. While removing the cover-tape, the tape is automatically feeded and the components, that should be placed next, are revealed.

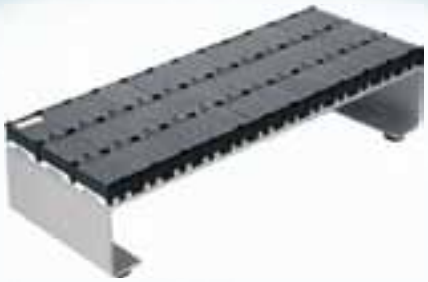


Tape strip feeder

This feeder type can handle a single strip of a component tape. Each part can be picked up directly from the tape, it isn't necessary to decante them into bulk containers first.

Bulk container

The patented bulk containers provide resistors, capacitors and ICs out of small containers to the machine.



HOTAIR 06

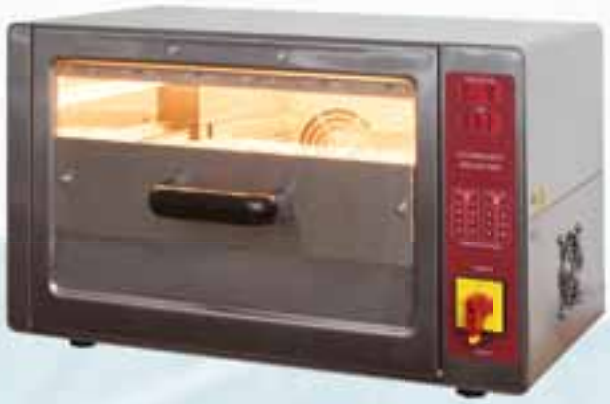
REFLOW OFEN

The HA06 is a solder oven for SMD component with the use of lead free paste.

The oven is work-ing with full convection forced air during the preheat stage. When the reflow stage is entered the heating will be done by hot air and quartz lamps.

The lamps are needed to get a short ramp speed. Once the reflow set point is reached the lamp power will be reduced to a minimum. At this point 85% of the heating is caused by forced hot air. This unique feature makes the oven suitable for solder big SMD components and/or components with pads under their casing while using lead free paste.

With good maintenance and proper use the oven will serve your solder needs for a long time with high quality solder results.



Some of the features include:

- Outstanding reflow soldering quality for SMD and hybrid
- ot air quartz oven Cures SMD adhesive
- Two heating zones
- Microprocessor controlled
- Reflow process view

HOTAIR 06

Power req.:	208/240 V1 phase 50/60 Hz
Rated power:	max. 3650 W
Dimensions (LxWxH):	550 x 490 x 335 mm
Max. Substrate surface:	300 mm x 370 mm
Number of heating zones:	2 zones microprocessor controlled
Preheat time:	0-999 sec.
Preheat temp:	60-260°C
Reflow Time:	0-999 sec.
Reflow temp:	90-300°C
Heat up time to thermal stabilization:	approx. 8 Minuten
Net weight:	18 kg
Options:	connection inert gas N2 with flow meter